



Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

CELL

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 1013 z(axial)

Communication System: CDMA-800, Frequency: 824.7 MHz, Duty Cycle: 1:1
 Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³
 Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010
 Sensor-Surface: 0mm (Fix Surface),
 Electronics: DAE4 Sn527, Calibrated: 7/8/2010
 Measurement SW: DASY4, V4.7 Build 80
 Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155041 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

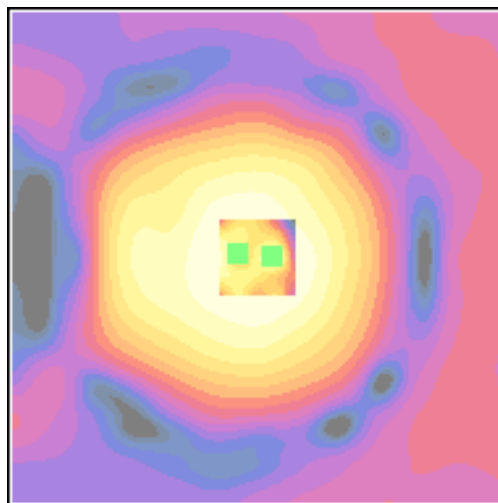
ABM1/ABM2 = 49.1 dB
 ABM1 comp = 4.30 dB A/m
 BWC Factor = 0.155041 dB
 Location: 2.1, -0.4, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155041 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.4 dB
 ABM1 comp = 3.80 dB A/m
 BWC Factor = 0.155041 dB
 Location: -1.6, 0, 3.7 mm



0 dB = 285.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 1013 x(longitudinal)

Communication System: CDMA-800, Frequency: 824.7 MHz, Duty Cycle: 1:1
 Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³
 Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010
 Sensor-Surface: 0mm (Fix Surface),
 Electronics: DAE4 Sn527, Calibrated: 7/8/2010
 Measurement SW: DASY4, V4.7 Build 80
 Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155041 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

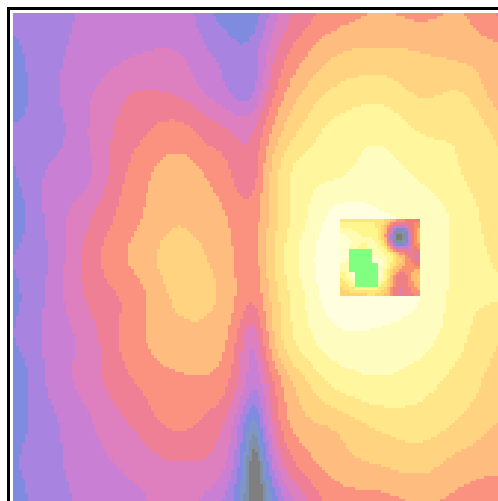
ABM1/ABM2 = 49.5 dB
 ABM1 comp = -4.06 dB A/m
 BWC Factor = 0.155041 dB
 Location: -10.4, 0.4, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155041 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.0 dB
 ABM1 comp = -5.50 dB A/m
 BWC Factor = 0.155041 dB
 Location: -11.3, 1.8, 3.7 mm



0 dB = 296.9

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 1013 y(transversal)

Communication System: CDMA-800, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.2 dB

ABM1 comp = -3.98 dB A/m

BWC Factor = 0.155041 dB

Location: 3.3, -4.6, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

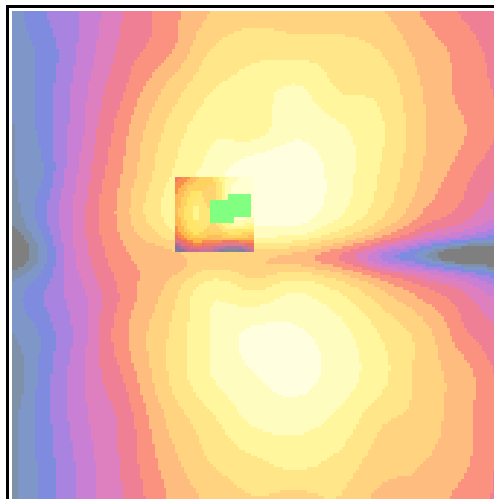
Cursor:

ABM1/ABM2 = 53.7 dB

ABM1 comp = -2.95 dB A/m

BWC Factor = 0.155041 dB

Location: 1.6, -5.2, 3.7 mm



0 dB = 409.3

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 383 z(axial)

Communication System: CDMA-800, Frequency: 836.49 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_383/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.2 dB

ABM1 comp = 5.06 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, 0.4, 3.7 mm

General Scans_383/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

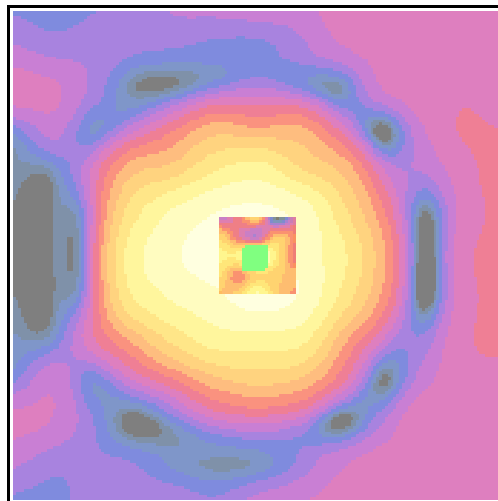
Cursor:

ABM1/ABM2 = 49.7 dB

ABM1 comp = 4.78 dB A/m

BWC Factor = 0.155979 dB

Location: 0, 0.2, 3.7 mm



0 dB = 323.3

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 383 x(longitudinal)

Communication System: CDMA-800, Frequency: 836.49 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_383/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.2 dB

ABM1 comp = -3.05 dB A/m

BWC Factor = 0.155979 dB

Location: -9.2, 0, 3.7 mm

General Scans_383/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

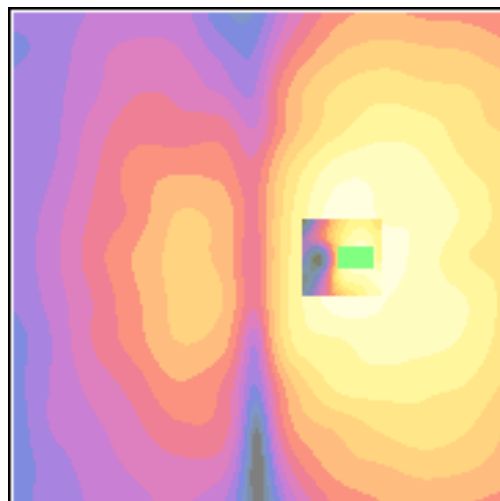
Cursor:

ABM1/ABM2 = 49.0 dB

ABM1 comp = -3.96 dB A/m

BWC Factor = 0.155979 dB

Location: -10.3, 0, 3.7 mm



0 dB = 290.0

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 383 y(transversal)

Communication System: CDMA-800, Frequency: 836.49 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_383/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 53.0 dB

ABM1 comp = -3.55 dB A/m

BWC Factor = 0.155979 dB

Location: 0, -5, 3.7 mm

General Scans_383/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

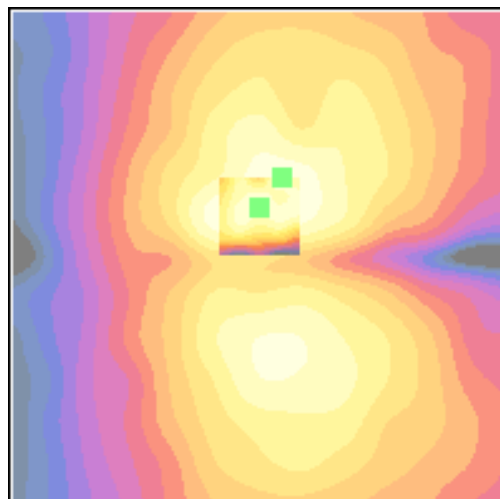
Cursor:

ABM1/ABM2 = 52.7 dB

ABM1 comp = -3.97 dB A/m

BWC Factor = 0.155979 dB

Location: -2.2, -8.2, 3.7 mm



0 dB = 447.6

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 777 z(axial)

Communication System: CDMA-800, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.4 dB

ABM1 comp = 4.40 dB A/m

BWC Factor = 0.155979 dB

Location: 0, 2.5, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

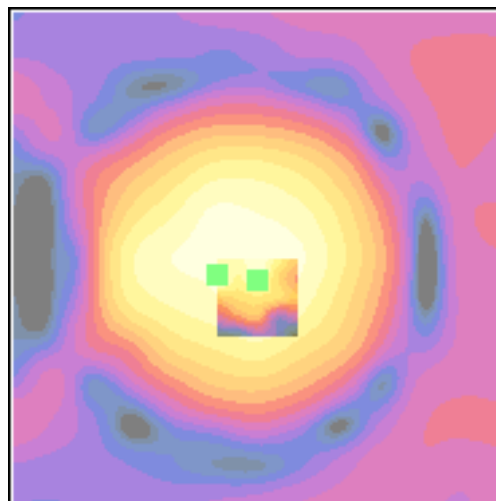
Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = 4.51 dB A/m

BWC Factor = 0.155979 dB

Location: 4, 2, 3.7 mm



0 dB = 296.5

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 777 x(longitudinal)

Communication System: CDMA-800, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB

ABM1 comp = -6.02 dB A/m

BWC Factor = 0.155979 dB

Location: -12.5, 0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

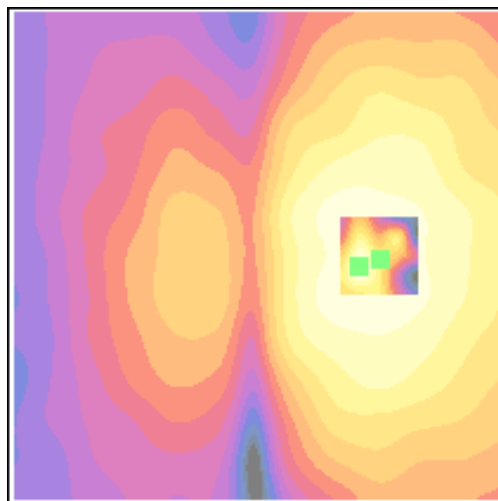
Cursor:

ABM1/ABM2 = 48.8 dB

ABM1 comp = -4.79 dB A/m

BWC Factor = 0.155979 dB

Location: -10.5, 1.2, 3.7 mm



0 dB = 273.8

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/23/2011

TCoil_FCC_Cell_S1350 Ch. 777 y(transveral)

Communication System: CDMA-800, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_777/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.6 dB

ABM1 comp = -3.41 dB A/m

BWC Factor = 0.155979 dB

Location: -0.4, -6.7, 3.7 mm

General Scans_777/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

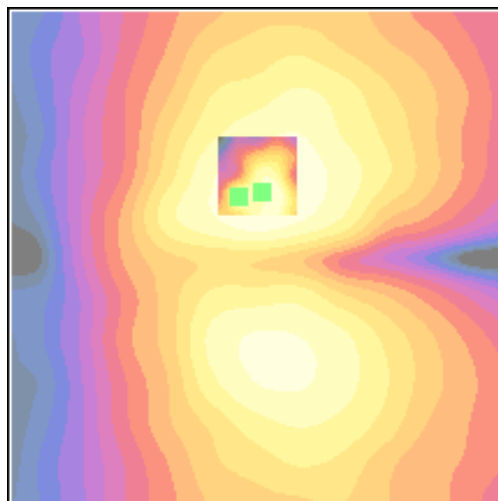
Cursor:

ABM1/ABM2 = 53.2 dB

ABM1 comp = -2.81 dB A/m

BWC Factor = 0.155979 dB

Location: 1.8, -6.1, 3.7 mm



0 dB = 425.9

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

AWS

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 25 z(axial)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = 4.41 dB A/m

BWC Factor = 0.155979 dB

Location: 0.8, 3.3, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

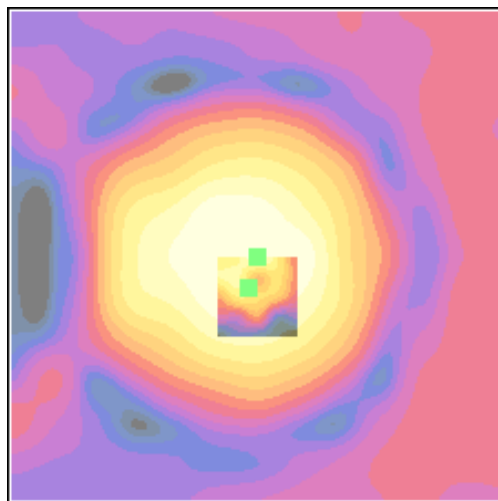
Cursor:

ABM1/ABM2 = 50.9 dB

ABM1 comp = 5.69 dB A/m

BWC Factor = 0.155979 dB

Location: 0, 0.2, 3.7 mm



0 dB = 290.5

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 25 x(longitudinal)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.0 dB

ABM1 comp = -4.27 dB A/m

BWC Factor = 0.155979 dB

Location: -9.6, 0.8, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

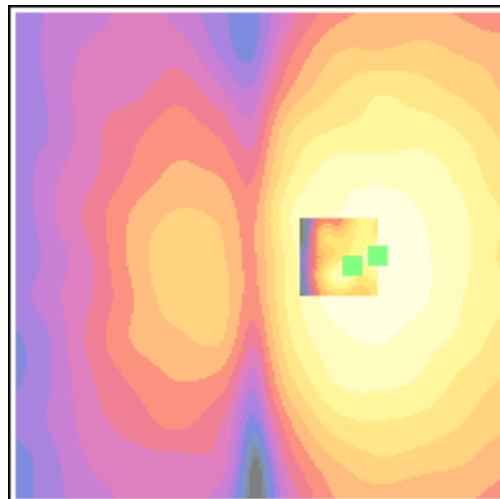
Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = -5.86 dB A/m

BWC Factor = 0.155979 dB

Location: -12.3, 0, 3.7 mm



0 dB = 282.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 25 y(transversal)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.4 dB

ABM1 comp = -3.50 dB A/m

BWC Factor = 0.155979 dB

Location: 2.9, -4.6, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

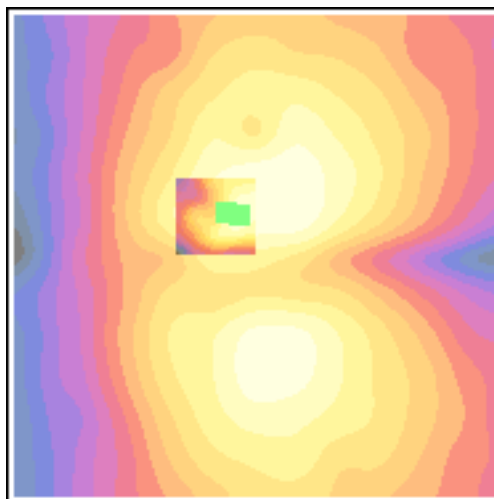
Cursor:

ABM1/ABM2 = 53.5 dB

ABM1 comp = -2.92 dB A/m

BWC Factor = 0.155979 dB

Location: 1.7, -4.4, 3.7 mm



0 dB = 418.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 450 z(axial)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_450/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.4 dB

ABM1 comp = 5.28 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, 0.8, 3.7 mm

General Scans_450/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

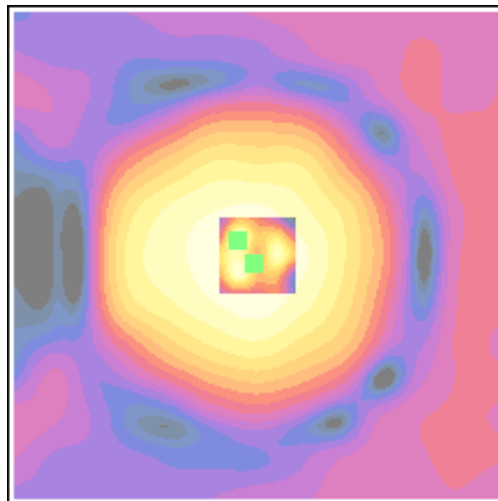
Cursor:

ABM1/ABM2 = 50.9 dB

ABM1 comp = 5.58 dB A/m

BWC Factor = 0.155979 dB

Location: 2, -1.6, 3.7 mm



0 dB = 331.7

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 450 x(longitudinal)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_450/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.0 dB

ABM1 comp = -4.27 dB A/m

BWC Factor = 0.155979 dB

Location: -9.2, 0.4, 3.7 mm

General Scans_450/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

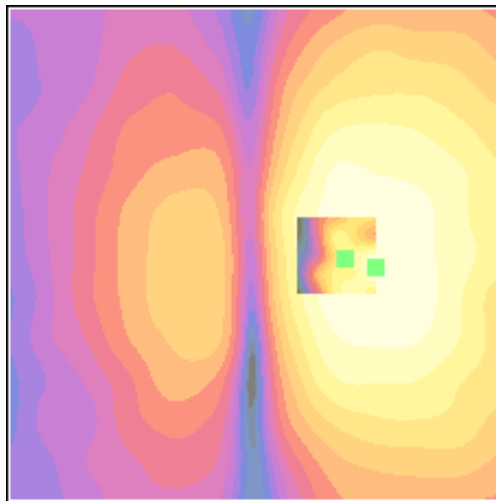
Cursor:

ABM1/ABM2 = 48.5 dB

ABM1 comp = -5.99 dB A/m

BWC Factor = 0.155979 dB

Location: -12.3, 1.2, 3.7 mm



0 dB = 252.5

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 450 y(transversal)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_450/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.0 dB

ABM1 comp = -2.87 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -5.8, 3.7 mm

General Scans_450/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

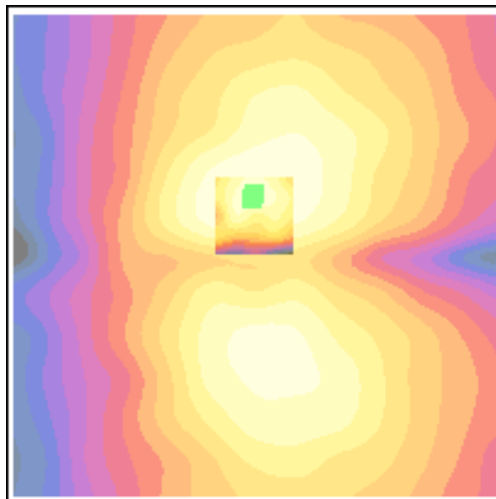
Cursor:

ABM1/ABM2 = 53.9 dB

ABM1 comp = -2.20 dB A/m

BWC Factor = 0.155979 dB

Location: 0, -6.4, 3.7 mm



0 dB = 399.5

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 875 z(axial)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_875/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.2 dB

ABM1 comp = 5.88 dB A/m

BWC Factor = 0.155979 dB

Location: 0, -0.8, 3.7 mm

General Scans_875/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

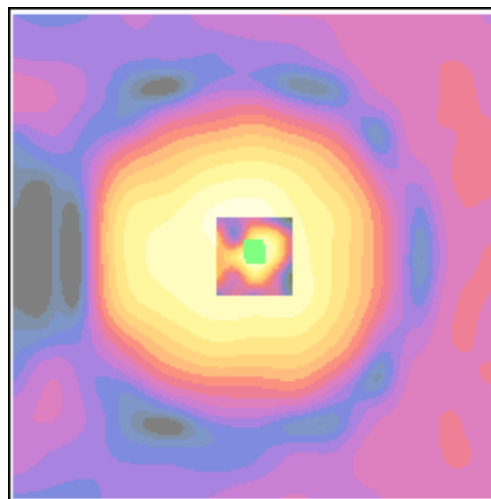
Cursor:

ABM1/ABM2 = 51.0 dB

ABM1 comp = 5.92 dB A/m

BWC Factor = 0.155979 dB

Location: -0.2, -0.2, 3.7 mm



0 dB = 363.0

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 875 x(longitudinal)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_875/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = -5.42 dB A/m

BWC Factor = 0.155979 dB

Location: -12.5, 0, 3.7 mm

General Scans_875/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

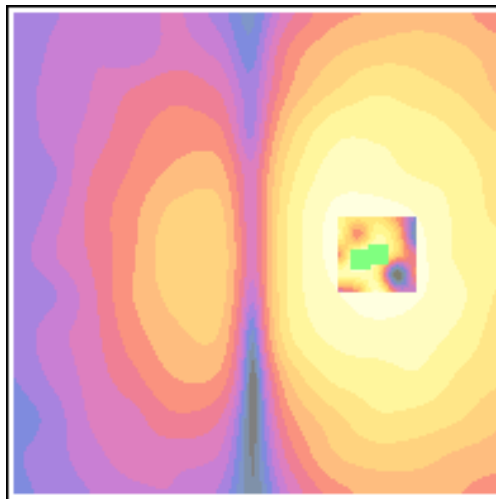
Cursor:

ABM1/ABM2 = 48.6 dB

ABM1 comp = -5.12 dB A/m

BWC Factor = 0.155979 dB

Location: -10.9, 0.6, 3.7 mm



0 dB = 290.1

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/24/2011

TCoil_FCC_AWS_S1350 Ch. 875 y(transversal)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_875/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.9 dB

ABM1 comp = -3.00 dB A/m

BWC Factor = 0.155979 dB

Location: -0.4, -6.3, 3.7 mm

General Scans_875/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

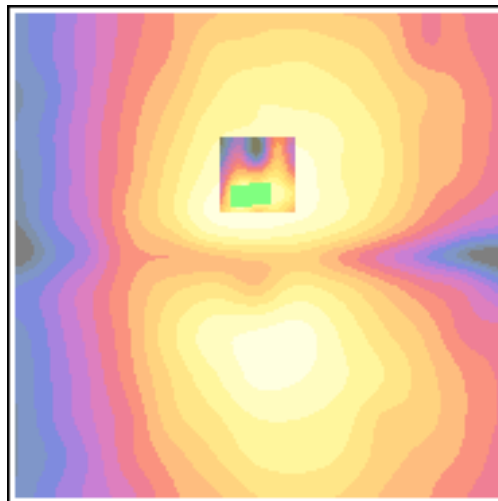
Cursor:

ABM1/ABM2 = 54.1 dB

ABM1 comp = -2.04 dB A/m

BWC Factor = 0.155979 dB

Location: 1.6, -6.1, 3.7 mm



0 dB = 441.7

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

PCS

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 25 z(axial)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.6 dB

ABM1 comp = 4.38 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

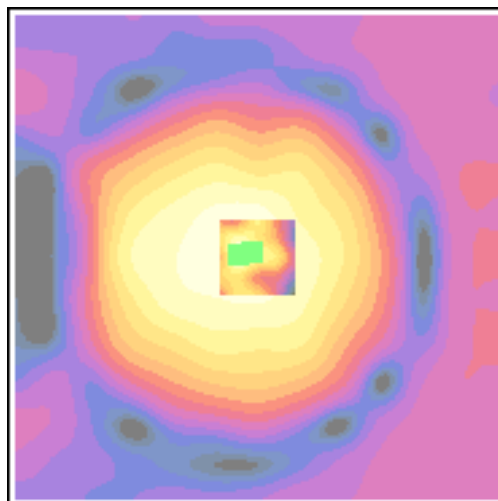
Cursor:

ABM1/ABM2 = 50.6 dB

ABM1 comp = 4.48 dB A/m

BWC Factor = 0.155979 dB

Location: 1.8, -0.4, 3.7 mm



0 dB = 339.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 25 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.0 dB

ABM1 comp = -4.11 dB A/m

BWC Factor = 0.155979 dB

Location: -9.2, 0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

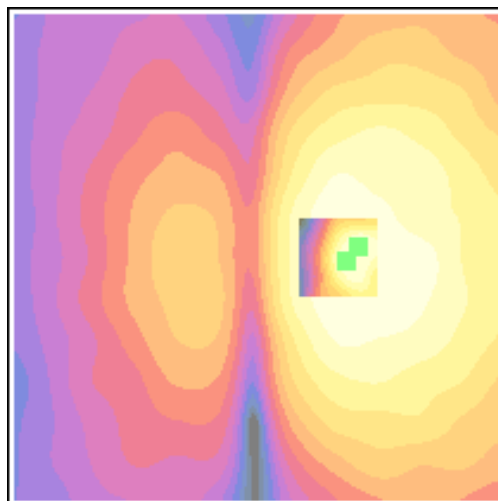
Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = -4.73 dB A/m

BWC Factor = 0.155979 dB

Location: -10.5, -1, 3.7 mm



0 dB = 280.8

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 25 y(transversal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.2 dB

ABM1 comp = -4.42 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -4.6, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

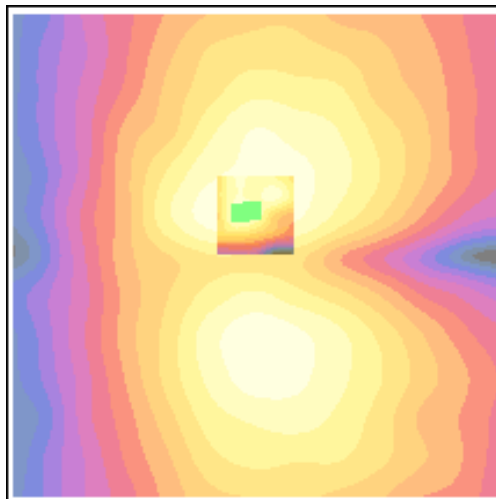
Cursor:

ABM1/ABM2 = 53.1 dB

ABM1 comp = -3.97 dB A/m

BWC Factor = 0.155979 dB

Location: 1.6, -4.4, 3.7 mm



0 dB = 408.2

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 600 z(axial)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
 Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³
 Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010
 Sensor-Surface: 0mm (Fix Surface),
 Electronics: DAE4 Sn527, Calibrated: 7/8/2010
 Measurement SW: DASY4, V4.7 Build 80
 Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155979 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

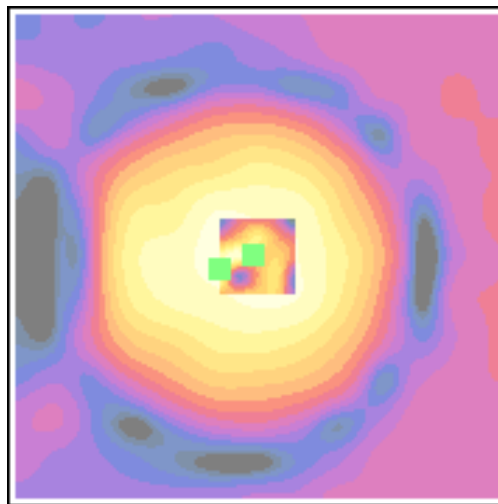
ABM1/ABM2 = 50.7 dB
 ABM1 comp = 4.72 dB A/m
 BWC Factor = 0.155979 dB
 Location: 0.4, 0, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155979 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.1 dB
 ABM1 comp = 4.00 dB A/m
 BWC Factor = 0.155979 dB
 Location: 4, 1.4, 3.7 mm



0 dB = 342.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 600 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = -3.13 dB A/m

BWC Factor = 0.155979 dB

Location: -9.2, -0.4, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

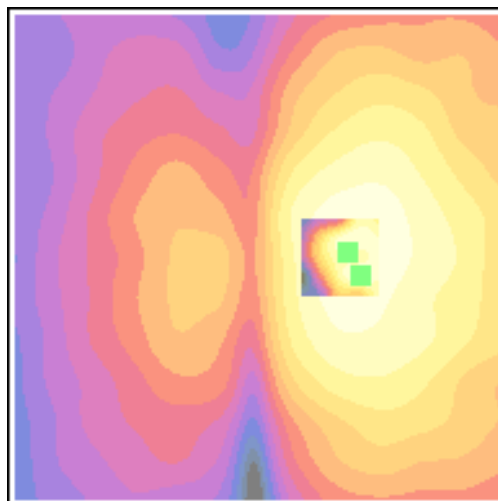
Cursor:

ABM1/ABM2 = 49.4 dB

ABM1 comp = -5.22 dB A/m

BWC Factor = 0.155979 dB

Location: -10.5, 1.8, 3.7 mm



0 dB = 326.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 600 y(transversal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.4 dB

ABM1 comp = -3.59 dB A/m

BWC Factor = 0.155979 dB

Location: -0.8, -7.1, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

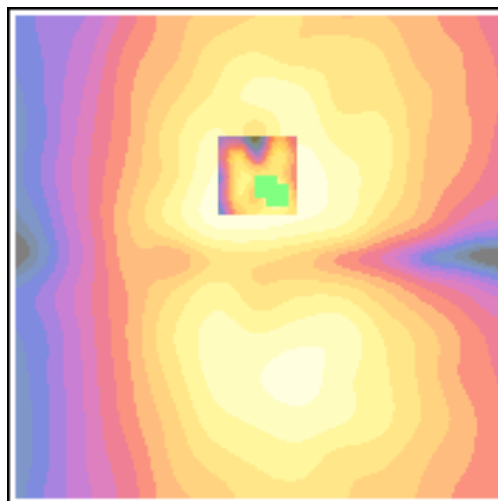
Cursor:

ABM1/ABM2 = 53.2 dB

ABM1 comp = -3.99 dB A/m

BWC Factor = 0.155979 dB

Location: -2, -6.3, 3.7 mm



0 dB = 370.7

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S13500 Ch. 1175 z(axial)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.6 dB

ABM1 comp = 3.86 dB A/m

BWC Factor = 0.155979 dB

Location: 3.3, 0, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

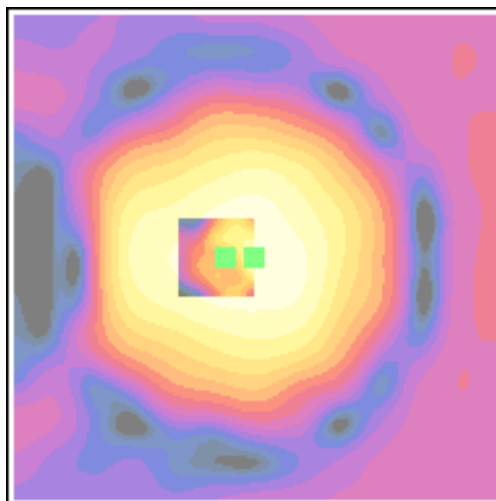
Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = 4.16 dB A/m

BWC Factor = 0.155979 dB

Location: 0.2, 0, 3.7 mm



0 dB = 303.4

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 1175 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.3 dB

ABM1 comp = -6.63 dB A/m

BWC Factor = 0.155979 dB

Location: -12.1, -2.5, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

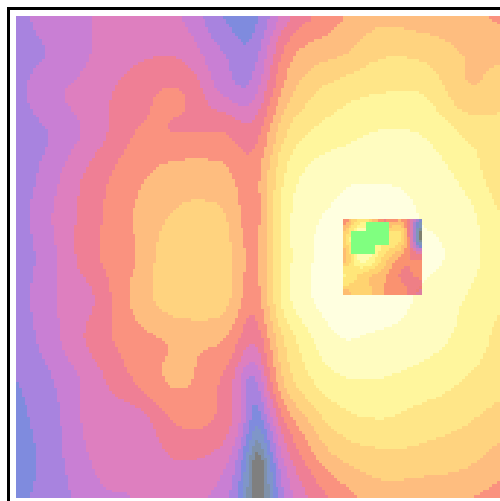
Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = -4.88 dB A/m

BWC Factor = 0.155979 dB

Location: -10.7, -1.6, 3.7 mm



0 dB = 259.5

Applicant	Kyocera
FCC ID:	OVFS13503CB
Report #:	CT-S1350-13C-0411-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 04/22/2011

TCoil_FCC_PCS_S1350 Ch. 1175 y(transversal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/6/2010

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/8/2010

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.8 dB

ABM1 comp = -4.39 dB A/m

BWC Factor = 0.155979 dB

Location: 2.9, -5.4, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

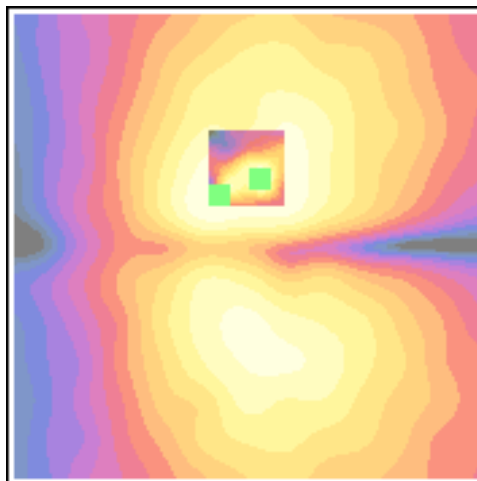
Cursor:

ABM1/ABM2 = 53.2 dB

ABM1 comp = -3.99 dB A/m

BWC Factor = 0.155979 dB

Location: -1.6, -7.1, 3.7 mm



0 dB = 388.1